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IN THE CLAIMS

Claim 1 (original): A method of fabricating a liquid crystal display panel, comprising the steps of:

preparing an upper substrate and a lower substrate;
bonding the upper substrate to the lower substrate;
cleaning exposed surfaces of the bonded upper and lower substrates; and
eliminating the exposed surfaces of the bonded upper and lower substrates.

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Claim 2 (original): The method according to claim 1, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 3 (original): The method according to claim 1, wherein the step of eliminating the exposed surfaces includes wet-etching.

Claim 4 (original): The method according to claim 1, further including the steps of:

forming a thin film transistor on the lower substrate;
forming a protective layer on the lower substrate; and
forming a pixel electrode on the protective layer to electrically contact the thin film transistor.

Claim 5 (currently amended): The method according to claim 4, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 6 (currently amended): The method according to claim 4, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, ~~Teflon~~⁷ TEFLON®, benzocyclobutene (BCB), ~~Cytop~~⁷ Cytop®, and perfluorocyclobutane (PFCB).

Claim 7 (original): The method according to claim 4, wherein the step of forming the thin film transistor includes:

forming a gate electrode on the lower substrate;

forming a gate insulating film on the lower substrate to cover the gate electrode;

forming an active layer on the gate insulating film; and

forming a source electrode and a drain electrode on the active layer.

Claim 8 (original): The method according to claim 7, wherein the source electrode and drain electrode contact the gate insulating film.

Claim 9 (currently amended): The method according to claim 7, wherein the pixel electrode contacts ~~parallel~~ flat and inclined surfaces of the drain electrode via a contact hole to expose the drain electrode.

Claim 10 (original): A method of fabricating a liquid crystal display panel, comprising the steps of:

- bonding an upper substrate to a lower substrate;
cleaning exposed surfaces of the bonded upper and lower substrates; and
removing the exposed surfaces of the bonded upper and lower substrates.

Claim 11 (original): The method according to claim 10, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 12 (original): The method according to claim 10, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 13 (original): The method according to claim 10, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 14 (original): A method of fabricating a liquid crystal display panel, comprising the steps of:

forming a gate electrode on a lower substrate;

forming a gate insulating film on the lower substrate to cover the gate

electrode;

forming an active layer on the gate insulating film; and

forming a source electrode and a drain electrode on the active layer;

bonding an upper substrate to the lower substrate;

cleaning exposed surfaces of the bonded upper and lower substrates; and

removing the exposed surfaces of the bonded upper and lower substrates.

Claim 15. (original): The method according to claim 14, wherein the step of cleaning exposed surfaces includes dry-etching.

Claim 16 (original): The method according to claim 14, wherein the step of removing the exposed surfaces includes wet-etching.

Claim 17 (original): The method according to claim 14, further including the steps of

forming a protective layer on the lower substrate; and

forming a pixel electrode on the protective layer to electrically contact the drain

electrode.

Claim 18 (currently amended): The method according to claim 17, wherein the pixel electrode is formed of a transparent conductive material including one of indium-tin-oxide (ITO), indium-zinc-oxide (IZO), and indium-tin-zinc-oxide (ITZO).

Claim 19 (currently amended): The method according to claim 17, wherein the protective layer is formed of an organic insulating material including one of an acrylic organic compound, ~~Teflon~~⁷ TEFLON®, benzocyclobutene (BCB), ~~Cytop~~⁷ CYTOP®, and perfluorocyclobutane (PFCB).

Claim 20 (original): The method according to claim 14, wherein the step of removing the exposed surfaces uniformly reduces a thickness of the liquid crystal display panel.

Claim 21 (new): The method according to claim 1, wherein the step of eliminating the exposed surfaces of the bonded upper and lower substrates uniformly reduces a thickness of the liquid crystal panel.
